

**Amendments to the Claims:**

This listing of claims represent all of the claims in this application:

**Listing of Claims:**

Claims 1-17 (canceled)

Claim 18. (original): A method of making a circuitized substrate assembly, said method comprising:

providing a first circuitized substrate including an opening therein;

providing a second circuitized substrate including an opening therein;

substantially filling said opening in said second circuitized substrate with a quantity of electrically conductive paste;

aligning said first and second circuitized substrates such that said opening in said second circuitized substrate having said electrically conductive paste therein aligns with said opening in said first circuitized substrate; and

bonding said first and second circuitized substrates together such that said electrically conductive paste only partly fills said opening in said first circuitized substrate while also substantially filling said opening in said second circuitized substrate.

Claim 19. (original) The method of claim 18 wherein said bonding of said first and second circuitized substrates is achieved by laminating.

Claim 20. (original) A method of making a circuitized substrate assembly, said method comprising:

providing a first circuitized substrate having an opening therein;

providing a second circuitized substrate having an opening therein;

positioning an electrically conductive cover member on a surface of said second circuitized substrate facing said first circuitized substrate to substantially cover said opening in said second circuitized substrate;

positioning a quantity of electrically conductive paste on said cover member;

aligning said first and second circuitized substrates such that said openings in said circuitized substrates are substantially aligned; and

bonding said first and second circuitized substrates such that said quantity of electrically conductive paste only partly fills said opening in said first circuitized substrate.

Claim 21. (original) The method of claim 20 wherein said bonding of said first and second substrates is achieved by laminating.